

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



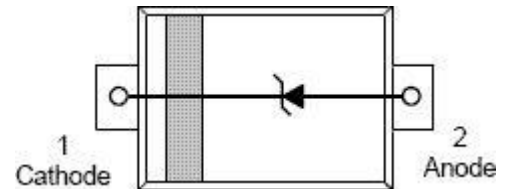
PLED

Product data sheet

Features

- Peak Reverse Working Voltage: 5V
- Low leakage current
- High ESD protection Level: >+/-15KV per HBM
- IEC61000-4-2 Level 4 ESD Protection
- IEC61000-4-4 Level 4 EFT Protection

SOD-523



Applications

- Cell phone handsets and accessories
- Personal Digital Assistants (PDAs)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Digital Cameras
- MP3/MP4/PMP Players

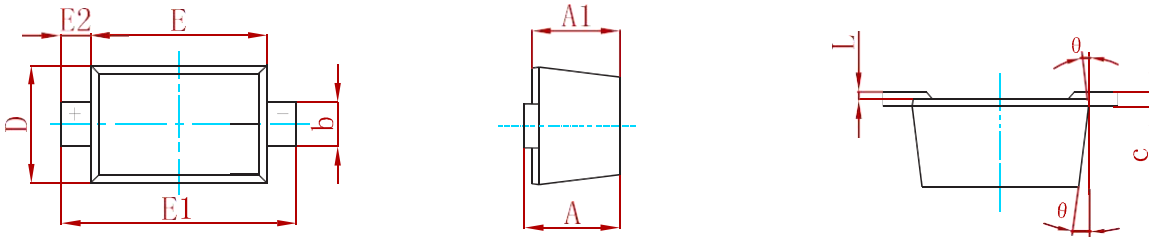
Rating	Symbol	Value	Units
Maximum peak pulse current (tp=8/20us)	I _{pp}	9.0	A
ESD Per IEC61000-4-2 (Air)	V _{pp}	+/-15	KV
ESD Per IEC61000-4-2 (Contact)		+/-10	
Maximum lead temperature for soldering during 10s	T _L	260	°C
Storage temperature range	T _{stg}	-55 to +150	°C
Operating temperature range	T _{op}	-55 to +150	°C

Electronics Characteristics

P/N	V _{RWM} (V)	I _R (μA) @ V _{RWM}	V _{BR} (V) @ I _T (Note 2)	I _T	C (pF)		V _C (V) @ I _{PP} = 1 A	V _C
	Max	Max	Min	mA	Typ	Max	Max	Per IEC61000-4-2
ESD5Z5VU-MS	5.0	1.0	6.2	1.0	0.5	0.9	8.0	Figures 2 and 3 See Below

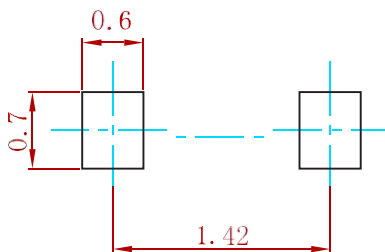
2. V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C.

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
0	7° REF		7° REF	

Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
ESD5Z5VU-MS	SOD-523	3000

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